

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6415174

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RAMJI SITARAMAN LAKSHMANAN	01/14/2020
BERNARD STENSON	01/15/2020
PADRAIG LIAM FITZGERALD	01/14/2020
OLIVER KIERSE	01/18/2020
MICHAEL JAMES TWOHIG	01/16/2020
RECEIVING PARTY DATA	
Name:	ANALOG DEVICES INTERNATIONAL UNLIMITED COMPANY
Street Address:	BAY F1 RAHEEN INDUSTRIAL ESTATE
City:	LIMERICK, CO. LIMERICK
State/Country:	IRELAND
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16951720
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	SCHWEGMAN LUNDBERG & WOESSNER, P.A.
Address Line 1:	P.O. BOX 2938
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	3867.629US1
NAME OF SUBMITTER:	DIANA JOHNSON
SIGNATURE:	/Diana Johnson/
DATE SIGNED:	11/23/2020
Total Attachments: 7	
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RECORDATION FORM COVER SHEET
PATENTS ONLY

Atty Ref/Docket No.: 3867.629US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Ramji Sitaraman Lakshmanan, Bernard Stenson, Padraig
Liam Fitzgerald, Oliver Kierse, Michael James Twohig

Additional name(s) of conveying party(ies) attached?

Yes No

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: January 14, 2020, January 15, 2020,
January 14, 2020, January 18, 2020, January 16, 2020

2. Name and address of receiving party(ies):

Name: Analog Devices International Unlimited
Company

Street Address: Bay F1 Raheen Industrial Estate

City: Limerick, Co. Limerick

Country: Ireland

Additional name(s) & address(es) attached? Yes
 No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 16/951,720

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: Trevor E. Lind

Address:

Schwegman Lundberg & Woessner, P.A.
P.O. Box 2938
Minneapolis, Minnesota 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

Enclosed

Authorized to be charged to deposit account
19-0743

8. Please charge any additional fees or credit any over
payments to our Deposit Account No.: 19-0743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy
of the original document.

Trevor E. Lind/Reg. No. 54,785

Name of Person Signing

/Trevor E. Lind/

Signature

November 20, 2020

Date

Total number of pages including cover sheet: 7

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Mail Stop Assignment Recordation Services
P.O. Box 1450
Alexandria, VA 22313-1450

PATENT
REEL: 054446 FRAME: 0358

ASSIGNMENT

WHEREAS, I am a named inventor, **Ramji Sitaraman Lakshmanan, Bernard Stenson, Pdraig Liam Fitzgerald, Oliver Kierse, Michael James Twohig**, of residence listed below, having invented certain new and useful improvements as described in an application for United States Letters Patent entitled "**INTEGRATED CIRCUIT PACKAGES TO MINIMIZE STRESS ON A SEMICONDUCTOR DIE**," (hereinafter referred to as "Application") and having internal reference number of **APD6728US01**.

WHEREAS, I hereby authorize and request the attorneys or agents associated with United States Patent and Trademark Office Customer No. **165378** to insert here in parentheses (Ser. No. 62/949,145; Filing Date: December 17, 2019) the filing date and serial number of the Application when known;

WHEREAS, **Analog Devices International Unlimited Company**, (hereinafter referred to as "Assignee"), a Corporation of **Ireland**, with an address of **Bay F1 Raheen Industrial Estate, Limerick, Co. Limerick, Ireland**, desires to acquire my entire right, title and interest in and to any and all inventions and improvements that are disclosed in the Application (hereinafter referred to as "Invention"), including any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign and transfer, and hereby agree to assign and transfer, to Assignee, all right, title and interest in and to the Invention and in and to the Application and all patents which may be granted therefrom, and all related applications (e.g., provisional applications, divisional applications, reissues, reexaminations, continuation applications, continuation-in-part applications, extensions thereof, design applications, applications in foreign countries, international applications, national phase applications, and the like). I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents, for the Invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also hereby assign and transfer, and hereby agree to assign and transfer to Assignee, all right, title and interest to the Invention, the Application or any related application throughout the world, including all rights of priority resulting from the filing of the Application or any related application, including but not limited to: the right to file applications and obtain patents, utility models, industrial models and designs for the Invention in Assignee's own name throughout the world, the right to claim priority from the Application or any related application when filing applications and obtaining patents, utility models, industrial models and designs for the Invention throughout the world, and all rights to publish cautionary notices reserving ownership of the Invention and all rights to register the Invention in appropriate registries. I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in and to Assignee.

ATTORNEY DOCKET NO.
3867.629PRV(APD6728US01)

ASSIGNMENT

I will communicate to Assignee any facts known to me respecting any improvements to the Invention; and I will sign all lawful papers, execute all rightful assignments, execute all provisional, divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in and to Assignee and to aid Assignee to obtain and enforce proper protection for the Invention in all countries and jurisdictions throughout the world. I irrevocably appoint Assignee as my attorney-in-fact to execute on my behalf any documents deemed necessary by Assignee to obtain and enforce proper protection for the Invention in all countries and jurisdictions throughout the world. I agree to testify and cooperate with Assignee in any judicial proceeding, administrative proceeding, post-grant proceeding, or other proceeding concerning the Invention (including litigation with a third party over any patent issued on the Invention), and Assignee agrees to cover my reasonable costs and expenses (if any).

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

Title of Invention:

INTEGRATED CIRCUIT PACKAGES TO
MINIMIZE STRESS ON A
SEMICONDUCTOR DIE

Full name of inventor:

Ramji Sitaraman Lakshmanan

Inventor's signature:

S. R. ji

Date:

14-Jan-2020

Inventor Home Address:

39 Mungret Woods, Mungret
Limerick, Co. Limerick V94 TW9N, Ireland

Witness's Print Name:

MICHAEL TWOHIG

Witness's signature:

Michael Twohig

Witness Home Address:

Aungleer, Mill Street,
Co. Cork, Ireland

ATTORNEY DOCKET NO.
3867.629PRV(APD6728US01)

ASSIGNMENT

Title of Invention:

INTEGRATED CIRCUIT PACKAGES TO
MINIMIZE STRESS ON A
SEMICONDUCTOR DIE

Full name of inventor:

Bernard Stenson

Inventor's signature:

B Stenson

Date:

15/11/2020

Inventor Home Address:

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Witness's Print Name:

MICHAEL TWONIG

Witness's signature:

Michael Twonig

Witness Home Address:

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ATTORNEY DOCKET NO.
3867.629PRV(APD6728US01)

ASSIGNMENT

Title of Invention:

INTEGRATED CIRCUIT PACKAGES TO
MINIMIZE STRESS ON A
SEMICONDUCTOR DIE

Full name of inventor:

Padraig Liam Fitzgerald

Inventor's signature:

Padraig Fitzgerald

Date:

19th January 2020

Inventor Home Address:

Lislehane Cullen
Mallow, CK, Ireland

Witness's Print Name:

MICHAEL TWOHIG

Witness's signature:

Michael Twohig

Witness Home Address:

AUNAGLOOR, MILLSTREET
Co. CORK, IRELAND

Title of Invention:

INTEGRATED CIRCUIT PACKAGES TO
MINIMIZE STRESS ON A
SEMICONDUCTOR DIE

Full name of inventor:

Oliver Kierse

Inventor's signature:



Date:

18 - April - 2010

Inventor Home Address:

Grange, Ballina
Kilaloe, Co Clare, Ireland

Witness's Print Name:

MARY KIERSE

Witness's signature:



Witness Home Address:

GEORGE, BALLINA
KILALOE, Co CLARE, IRELAND

ATTORNEY DOCKET NO.
3867.629PRV(APD6728US01)

ASSIGNMENT

Title of Invention:

INTEGRATED CIRCUIT PACKAGES TO
MINIMIZE STRESS ON A
SEMICONDUCTOR DIE

Full name of inventor:

Michael James Twohig

Inventor's signature:

Michael Twohig

Date:

11-01-2020

Inventor Home Address:

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Co. Cork, CK, Ireland

Witness's Print Name:

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Witness's signature:

Padraig Fitzgerald

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LISLEHANE, CULLEN,
MALLOO, Co. COCK,
IRELAND